

SPECIFICATION AND PERFORMANCE

Series	104D-RCA0-RA1	File	104D-RCA0-RA1_SPEC_2	Date	2026/08/26
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Scope:

This specification covers the requirements for product performance, test methods and quality assurance provisions of **104D-RCA0-RA1**

Performance and Descriptions:

The product is designed to meet the electrical, mechanical and environmental performance requirements specification. Unless otherwise specified, all tests are performed at ambient environmental conditions.

RoHS:

All material in according with the RoHS environment related substances list controlled.

MATERIALS

NO.	PART NAME	DESCRIPTION
1	HOUSING	LCP, Color Black
2	SLIDER CAM	
3	PLASTIC FRAME	
4	CONTACT-SD	Phosphor Bronze Alloy 0.15T, 5u"min Gold plating on contact area, 80u"min Tin plating on solder area, 30u"min Nickel under plating over all.
5	PROTECT CONTACT	
6	PROTECT CONTACT AND DETECT CONTACT-SWITCH	
7	DETECT CONTACT	Brass, 0.2T, 80u" min. Tin plating on solder tail area, 30u" min. Nickel under plating overall
8	HOLDDOWN CONTACT	
9	SHELL	Stainless 0.2T
10	CARD LOCK	
11	CAM PIN	Stainless wire, Φ0.4
12	SPRING	Piano wire, Φ0.25, 50u" min. Nickel under plating over all

RATING

Voltage Rating	100V AC/DC
Current Rating	0.5A (Max.)/(1PIN)
Operating Temperature	-40°C to + 85°C
Storage Temperature	-40°C to +85°C
Durability	10,000 cycles



ELECTRICAL

Item	Requirement	Test Condition
Contact Resistance	Initial: 100 mΩ (Max)	Solder connectors on PCB and mate them together, measure by applying closed circuit current of 10mA maximum at open circuit voltage of 20mV (max). (JIS C5402 5.4)
Insulation Resistance	Initial: 1,000MΩ(Min).	Apply 100V DC between adjacent contacts, or contact and ground. (MIL-STD-202 METHOD 302)
Dielectric Withstanding Voltage	No breakdown	Mate connectors; apply 500V AC(rms.) between two adjacent for 1minute. (Trip current:1mA) (MIL-STD-202 METHOD 301)

MECHANICAL

Item	Requirement	Test Condition
Contact Retention Force	2.45N per pin (Min.)	Place a connector on the push-pull machine, then apply a force on a contact head and push the contact to the opposite direction of the contact insertion at the speed of 25 ± 3 mm/min. (EIA364-29)
Durability	Contact Resistance: 100mΩ(Max) No Damage	Solder connectors on PCB, then place them on the pull-push machine, and repeat mating and un-mating 10,000cycles repeatedly at a rate of 400~600 cycles/hour. (EIA364-09)
Vibration	Finish 1. No electrical discontinuity more than 0.1μs. 2 .No Damage 3.Contact Resistance 100mΩ(Max)	Mate dummy card and subject to the following vibration conditions, for a period of 30 minutes in each of 3 mutually perpendicular axis, passing DC 1 mA during the test. Amplitude: 1.52 mm P-P or 19.6 m/s ² Frequency: 10-55-10Hz Shall be traversed in 1minute. (MIL-STD-202 METHOD 201)
Shock	Finish 1. No electrical discontinuity more than 0.1μs. 2 .No Damage 3.Contact Resistance 100mΩ(Max)	Solder connectors on PCB and mate them together, subject to the following shock conditions, 3 shocks shall be period along 3 mutually perpendicular axis, passing DC 1mA current during the test. 1 axis, plus-minus direction, core 3 times. (total:18times) 490m/s ² (MIL-STD-202 METHOD 213)
Card Insertion / Eject Force	4.2 kgf (Max)	Push the card at the speed rate 25 ± 3 mm/minute.
Card Release Force	0.21 kgf Min.	From the state of the card lock, Pull the card at the speed rate 25 ± 3 mm/minute.
Push in strength	No Damage	The card inserted in positive and the opposite direction and the load of 30N is added

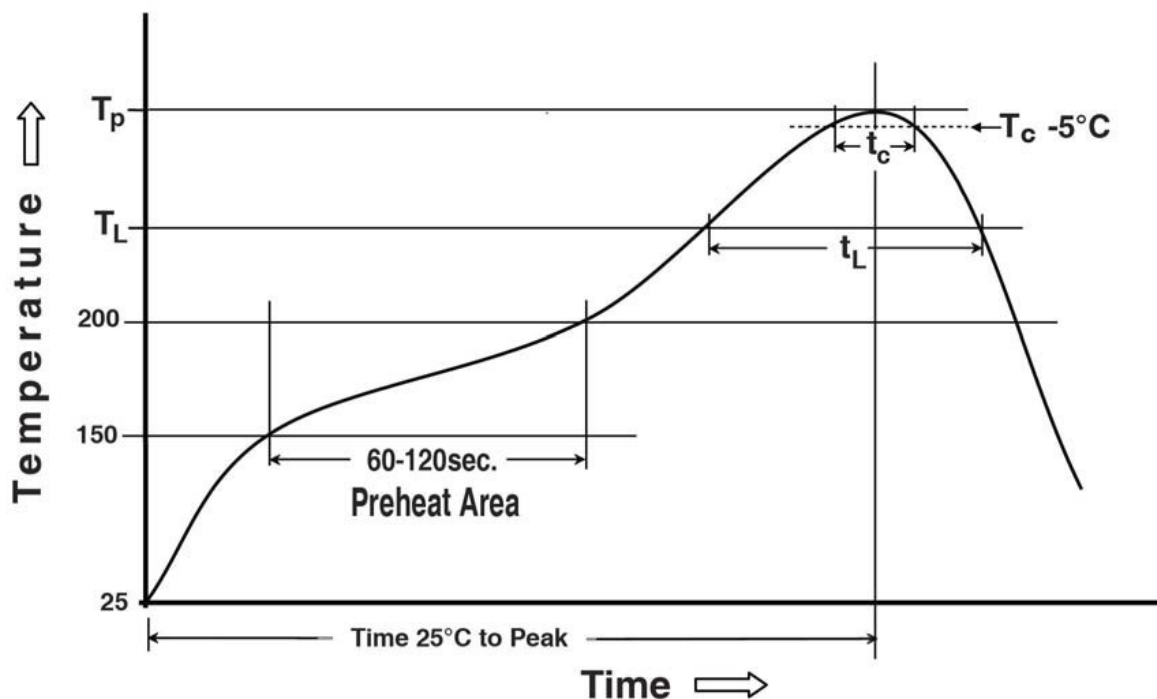


ENVIRONMENTAL		
Item	Requirement	Test Condition
Temperature Cycle	Finish 1.Contact Resistance 100mΩ(Max) 2.Insulation Resistance 100MΩ(Min)	Stage Temp Time t1 -55°C 30 min t2 -55~+90°C 3 min t3 +90°C 30 min t4 +90~-55°C 3 min Test time: 6 cycles (JIS C0025)
Heat Resistance	Finish 1. Contact Resistance: 100mΩ(Max) 2.Insulation Resistance 100MΩ(Min)	Solder connectors on PCB and mate them together, expose to 90 ± 2°C for 96hrs. Upon completion of the exposure period, the test specimens shall be conditioned at ambient room conditions for 1 of 2hrs, after which the specified measurements shall be performed. (MIL-STD-202 METHOD 108)
Cold Resistance	Finish 1. Contact Resistance: 100mΩ(Max) 2. Insulation Resistance 100MΩ(Min)	Solder connectors on PCB and mate them together, expose to -55 ± 3°C for 96hrs. Upon completion of the exposure period, the test specimens shall be conditioned at ambient room conditions for 1 of 2hrs, after which the specified measurements shall be performed. (EIA364-59)
Humidity	Finish 1. Contact Resistance: 100mΩ(Max) 2. Insulation Resistance 100MΩ(Min)	Humidity storage at +40°C with 90~95% RH for 96 hours. Upon completion of the exposure period, the test specimens shall be conditions for 1 of 2 hrs, then 10 mating cycles while. (EIA364-31)
Salt Spray	Finish 1. Contact Resistance: 100mΩ(Max)	5 ± 1% salt solutions, at 35 ± 2°C duration 48 hours. Connectors detached (MIL-STD-1344)

SOLDER ABILITY		
Item	Requirement	Test Condition
Solder ability	95% of immersed area must show no voids, pin holes.	DIP solder tails into the molten solder (held at 230±5°C) up to 0.5mm from the tip of tails for 3±0.5 seconds. (MIL-STD-202 METHOD 208)
Resistance to soldering heat	No melting, cracks or functional damage allowed	All connectors designed for PCB soldering within this specification must be able to withstand the heat from solder oven according to the graph below. The cycle should be repeated twice. (MIL-STD-202 METHOD 210)



Reflow Profile



Preheating temperature: 150 ~ 200°C, 60~120 seconds

Liquidus temperature (T_L): 217°C, 60~150 seconds

Peak temperature: 260°C

Time within 5 °C of peak temperature (T_c): 255°C, 30seconds